



PATENT  
8013-1147

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of

Hirokazu HONDA

Conf. 7187

Application No. 09/678,609

Group 2822

Filed October 4, 2000

Examiner David E. Graybill

MULTILAYER INTERCONNECTION BOARD, SEMICONDUCTOR  
DEVICE HAVING THE SAME, AND METHOD OF FORMING THE  
SAME AS WELL AS METHOD OF MOUNTING THE SEMICONDUCTOR  
CHIP ON THE INTERCONNECTION BOARD

RESPONSE

Assistant Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

February 17, 2005

Sir:

In response to the Office Action mailed November 12,  
2004, the applicant and assignee provide the requested  
information.

The Claims are listed in the listing that begins on  
page 2 of this paper.

Remarks begin on page 12 of this paper.